

We claim:

1. A power semiconductor module, comprising:

semiconductor components;

a plastic housing having an interior and connecting element openings formed therein;

a substrate disposed in said plastic housing defining a housing base of said plastic housing, said substrate containing a ceramic plate having a top side and a bottom side with a top metallization layer disposed on said top side and a bottom metallization layer disposed on said bottom side, said top metallization layer facing said interior of said plastic housing being patterned in order to form interconnects and equipped for and receiving said semiconductor components;

connecting elements interconnecting said semiconductor components; and

terminal elements for providing external terminals press-fitted into said connecting element openings in said plastic housing.

2. The power semiconductor module according to claim 1,

wherein said plastic housing has an inner side and said terminal elements have lugs which bear on said inner side for fixing said terminal elements in position.

3. The power semiconductor module according to claim 1, wherein said terminal elements run approximately parallel to said housing base in said interior of said plastic housing.

4. The power semiconductor module according to claim 1, wherein said plastic housing includes a frame and a cover.

5. The power semiconductor module according to claim 4, wherein said terminal elements are disposed in said frame.

6. The power semiconductor module according to claim 1, wherein said substrate is covered with a potting compound.

7. The power semiconductor module according to claim 6, wherein said potting compound is formed of a soft potting compound layer and a hard potting compound disposed on said soft potting compound.